

Local Supports in the US

Seven activities in “Local Supports”

- 1 I-beam design, fabrication (LBNL)
- 2 Stave cooling services (ANL)
- 3 Stave thermal testing (SLAC)
- 4 Stave loading (SLAC)
- 5 End-of-stave (EoS) interface card (SLAC)
- 6 Flex circuit for power and data in outer layers (UNM)
- 7 Twisted pair (TWP) cable for data in inner layers (UCSC)

Core assumptions

- **I-beams chosen for barrel supports** (affects: 1–3,4–7)
- EoS card is “active” (affects: 5)
- TWP used for inner layer (affects: 7)